



PRE-RELEASE VERSION (FDIS)



**Test methods for electrical materials, printed board and other interconnection structures and assemblies –
Part 2-808: Thermal resistance of an assembly by thermal transient method**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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NOTE FROM TC/SC OFFICERS:

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-808: Thermal resistance of an assembly by thermal transient method

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IEC 61189-2-808 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed board and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-808: Thermal resistance of an assembly by thermal transient method

1 Scope

This part of IEC 61189 describes the thermal transient method to characterize the thermal resistance of an assembly consisting of a heat source (e.g. power device), an attachment material (e.g. solder) and a dielectric layer with electrode. This method is suitable to determine the thermal resistance of materials and assembly methods as well as to optimize the thermal flux to a heat sink.

NOTE This method is not intended to measure and specify the value of the thermal resistance of a dielectric material. For that purpose, other standards exist. Examples are given in Annex A.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194-2, *Printed boards design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*